



recommended by ASTM B 545 and 579. ASTM B 488 also recommends a 50 $\mu$ " min. nickel barrier plate beneath gold to prevent copper diffusion inherent with all copper alloy products.

†RoHS-2 directive 2011/65/EU, exemption 6c allows up to 4% lead as an alloy agent in copper.

\*International Annealed Copper Standard, i.e. as a % of pure copper.

## INSULATOR MATERIAL:

### Nylon 46 (Injection Molded)

Properties:


- High Temp. {30% glass filled} or {45% glass filled}, (black). Flammability rating UL 94 V-0
- Material Heat Deflection Temp. (per ASTM D 648): 554°F (290°C) @ 264 psi

Note: Materials with HDT above 446°F (230°C) are considered suitable for "eutectic" reflow soldering. For "lead-free" reflow soldering, choose materials with an HDT above 500°F (260°C).

## ADDITIONAL NOTES & SPECIFICATIONS

In the interest of improved design, quality and performance, Mill-Max reserves the right to make changes in its specifications without prior notice. Specifications and tolerances are provided wherever possible. Due to the wide variety of interconnects Mill-Max offers, the specific tolerances vary from product to product. If you need information regarding the tolerance of a particular part, please contact Technical Services.

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190 Pine Hollow Rd , Oyster Bay, NY 11771, USA  
Phone: 516.922.6000

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